

TOSHIBA CCD Linear Image Sensor CCD (charge coupled device)

TCD1304DG

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The TCD1304DG is a high sensitive and low dark current 3648 elements linear image sensor. The sensor can be used for POS scanner.

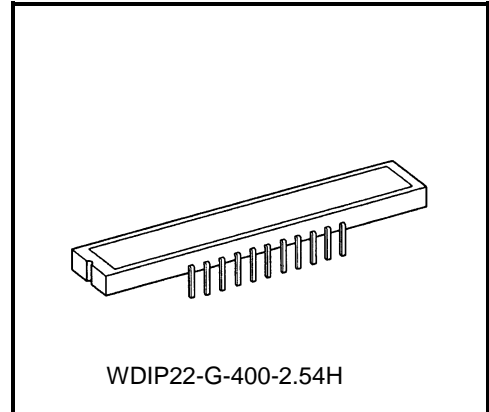
The device consist of sensitivity CCD chip.

The TCD1304DG has electronic shutter function (ICG).

Electronic shutter function can keep always output voltage constant that vary with intensity of lights.

FEATURES

- Pixel Number : 3648
- Pixel Size : 8μm×200μm (8μm pitch)
- Photo Sensing Region : High Sensitive & Low Dark Current pn Photodiode
- Internal Circuit : CCD Drive Circuit
- Power Supply : Only 3.0V Drive (MIN)
- Function : Electronic Shutter
Sample and Hold Circuit
- Package : 22 Pin CERDIP



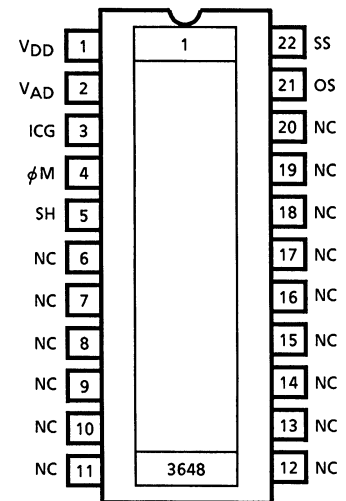
Weight: (3.5g (Typ.))

ABSOLUTE MAXIMUM RATINGS (Note 1)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Master Clock Pulse Voltage	$V_{\phi M}$	-0.3 to +7.0	V
SH Pulse Voltage	V_{SH}		
ICG Pulse Voltage	V_{ICG}		
Digital Power Supply	V_{DD}		
Analog Power Supply	V_{AD}		
Operating Temperature	T_{opr}	-25 to +60	°C
Storage Temperature	T_{stg}	-40 to +100	°C

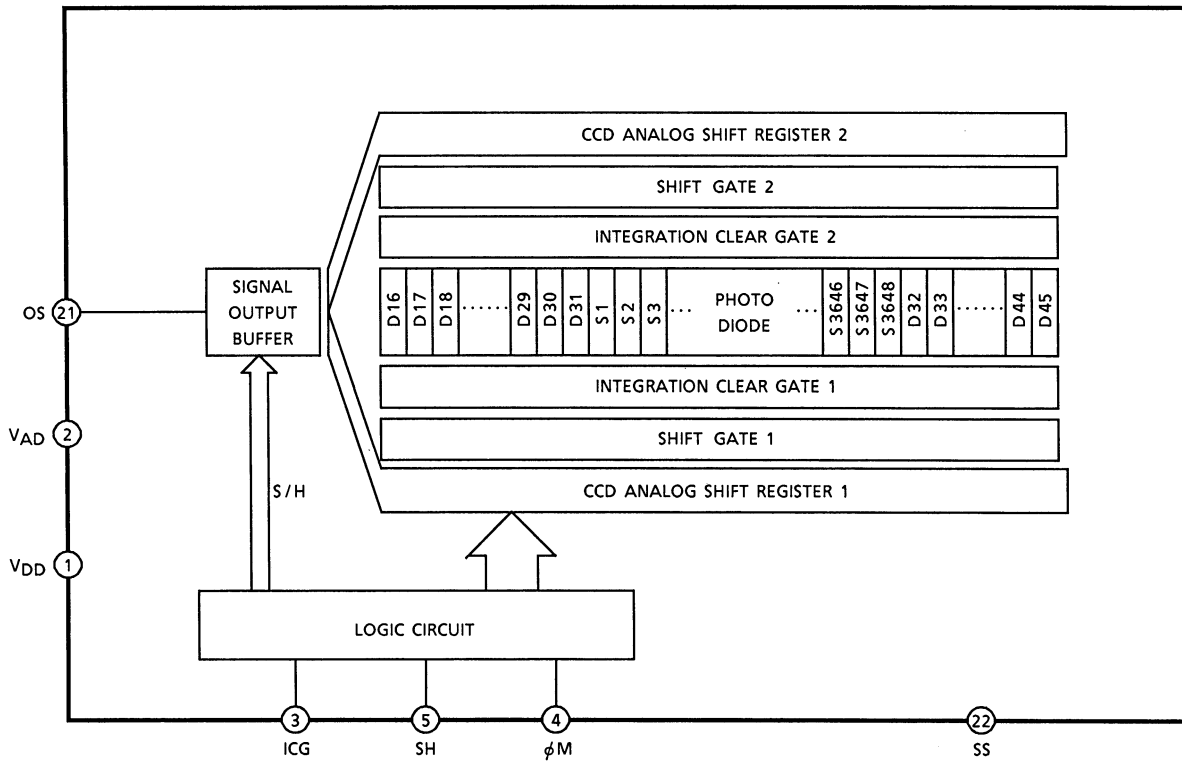
Note: All voltage are with respect to SS terminals. (Ground)
 None of the ABSOLUTE MAXIMUM RATINGS must be exceeded, even instantaneously.
 If any one of the ABSOLUTE MAXIMUM RATINGS is exceeded, the electrical characteristics, reliability and life time of the device cannot be guaranteed.
 If the ABSOLUTE MAXIMUM RATINGS are exceeded, the device can be permanently damaged or degraded.
 Create a system design in such a manner that any of the ABSOLUTE MAXIMUM RATINGS will not be exceeded under any circumstances.

PIN CONNECTION



(TOP VIEW)

CIRCUIT DIAGRAM



PIN NAMES

PIN No.	SYMBOL	NAME	PIN No.	SYMBOL	NAME
1	VDD	Power (Digital)	22	SS	Ground
2	VAD	Power (Analog)	21	OS	Output signal
3	ICG	Integration clear gate	20	NC	Non connection
4	φM	Master clock	19	NC	Non connection
5	SH	Shift gate	18	NC	Non connection
6	NC	Non connection	17	NC	Non connection
7	NC	Non connection	16	NC	Non connection
8	NC	Non connection	15	NC	Non connection
9	NC	Non connection	14	NC	Non connection
10	NC	Non connection	13	NC	Non connection
11	NC	Non connection	12	NC	Non connection

OPTICAL / ELECTRICAL CHARACTERISTICS

Ta = 25°C, V_φ = 4.0V (PULSE), f_{DATA} = 0.5MHz, t_{INT} (INTEGRATION TIME) = 10ms, V_{AD} = V_{DD} = 4.0V, LIGHT SOURCE = DAYLIGHT FLUORESCENT LAMP

CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Sensitivity	R	110	160	—	V / lx·s	
Photo Response Non Uniformity	PRNU	—	—	10	%	(Note 1)
Register Imbalance	RI	—	—	3	%	(Note 2)
Saturation Output Voltage	V _{SAT}	450	600	—	mV	(Note 3)
Dark Signal Voltage	V _{MDK}	—	2	5	mV	(Note 4)
Total Transfer Efficiency	TTE	92	95	—	%	
Dynamic Range	DR	—	300	—	—	(Note 5)
Saturation Exposure	SE	—	0.004	—	lx·s	(Note 6)
DC Power Dissipation	PD	—	25	75	mW	
DC Signal Output Voltage	V _{OS}	1.5	2.5	3.5	V	(Note 7)
Output Impedance	Z _O	—	0.5	1.0	kΩ	
Image Lag of Electronic Shutter	V _{LAGICG}	—	—	10	mV	t _{INT} =100μs

Note 1: Measured at 50% of SE (Typ.)

Definition of PRNU:

$$PRNU = \frac{\Delta X}{\bar{X}} \times 100 (\%)$$

Where \bar{X} is average of total signal outputs and ΔX is the maximum deviation from \bar{X} under uniform illumination.

Note 2: Measured at 50% of SE (Typ.)

RI is defined as follows:

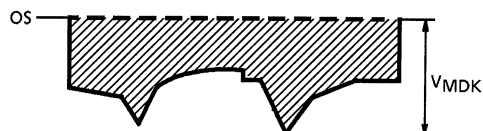
$$RI = \frac{\Delta Y}{\bar{X}} \times 100(\%)$$

Where \bar{X} is average of total signal output.

ΔY : | (average of odd signal output) – (average of even signal output) |

Note 3: V_{SAT} is defined as minimum saturation output voltage of all effective pixels. V_{AD}=V_{DD}=3.0V.

Note 4: V_{MDK} is defined as maximum dark signal voltage of all effective pixels.



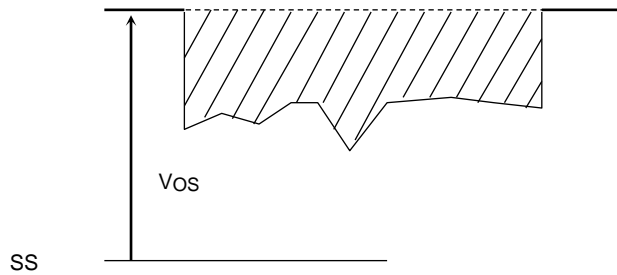
Note 5: Definition of DR : $DR = \frac{V_{SAT}}{V_{MDK}}$

VMDK is proportional to t_{INT} (Integration time).

So the shorter t_{INT} condition makes wider DR value.

Note 6: Definition of SE : $SE = \frac{V_{SAT}}{R} (I \cdot S)$

Note 7: DC signal output voltage is defined as follows:



OPERATING CONDITIONS

For best performance, the device should be used within the Recommended Operating Conditions.

CHARACTERISTIC		SYMBOL	MIN	TYP.	MAX	UNIT
Master Clock Pulse Voltage	"H" Level	$V_{\phi M}$	3.0	4.0	5.5	V
	"L" Level		0	0	0.44	
SH Pulse Voltage	"H" Level	V_{SH}	3.0	4.0	5.5	V
	"L" Level		0	0	0.44	
ICG Pulse Voltage	"H" Level	V_{ICG}	3.0	4.0	5.5	V
	"L" Level		0	0	0.44	
Digital Power Supply		V_{DD}	3.0	4.0	5.5	V
Analog Power Supply		V_{AD}	3.0	4.0	5.5	V

Note: $V_{AD} = V_{DD}$

MAX Voltage of Pulse Voltage "H" Level = $V_{DD} = V_{AD}$

MIN. Voltage of Pulse Voltage "H" Level = $V_{DD} - 0.5V = V_{AD} - 0.5V$

CLOCK CHARACTERISTICS ($T_a = 25^\circ\text{C}$) ($V_{AD} = V_{DD} \geq 4.0V$)

For best performance, the device should be used within the Recommended Operating Conditions.

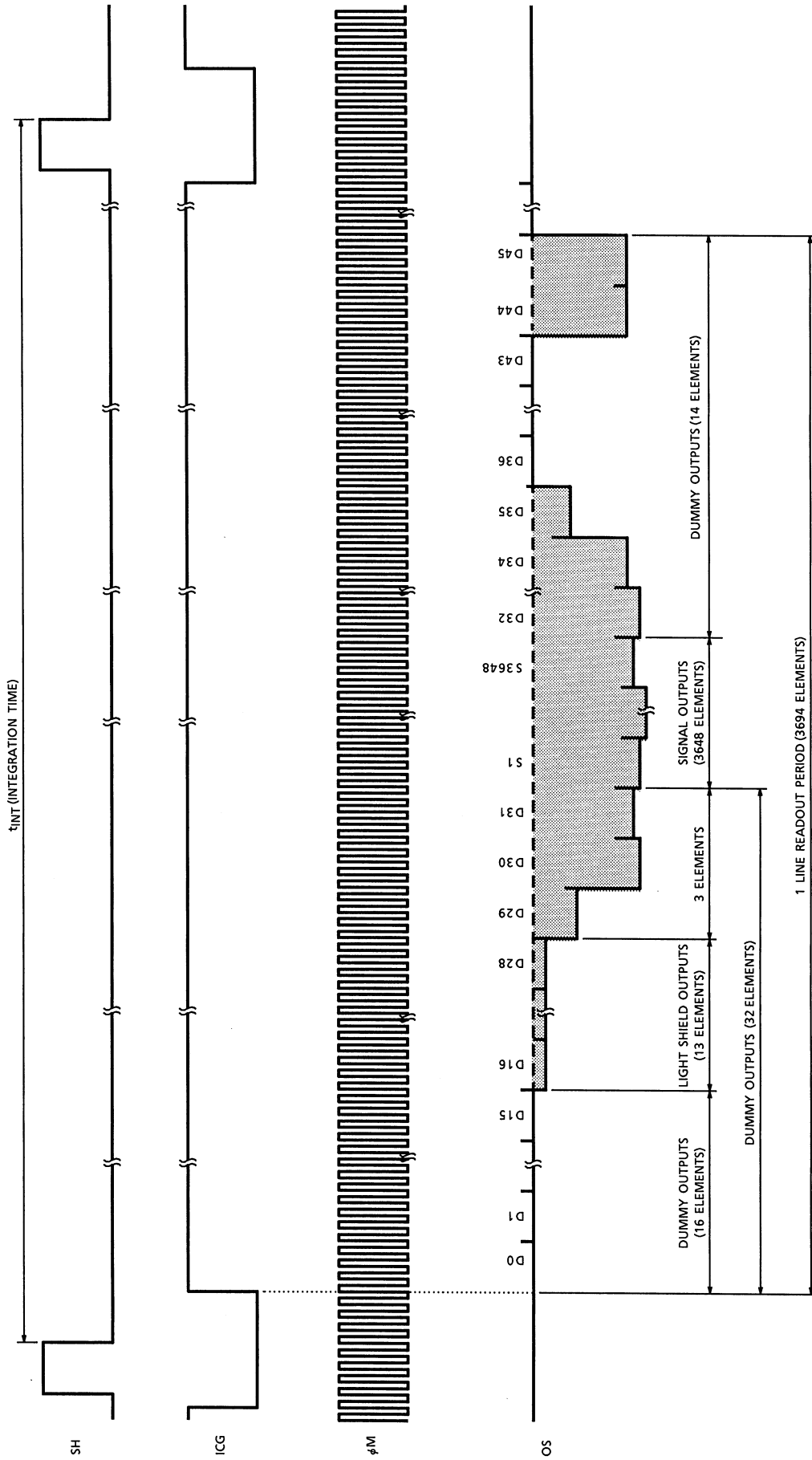
CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Master Clock Frequency	$f_{\phi M}$	0.8	2.0	4.0	MHz
Data Rate	f_{DATA}	0.2	0.5	1.0	MHz
Master Clock Capacitance	$C_{\phi M}$	—	10	—	pF
Shift Pulse Capacitance	C_{SH}	—	600	—	pF
ICG Pulse Capacitance	C_{ICG}	—	250	—	pF

CLOCK CHARACTERISTICS ($T_a = 25^\circ\text{C}$) ($3.0V \leq V_{AD} = V_{DD} < 4.0V$)

For best performance, the device should be used within the Recommended Operating Conditions.

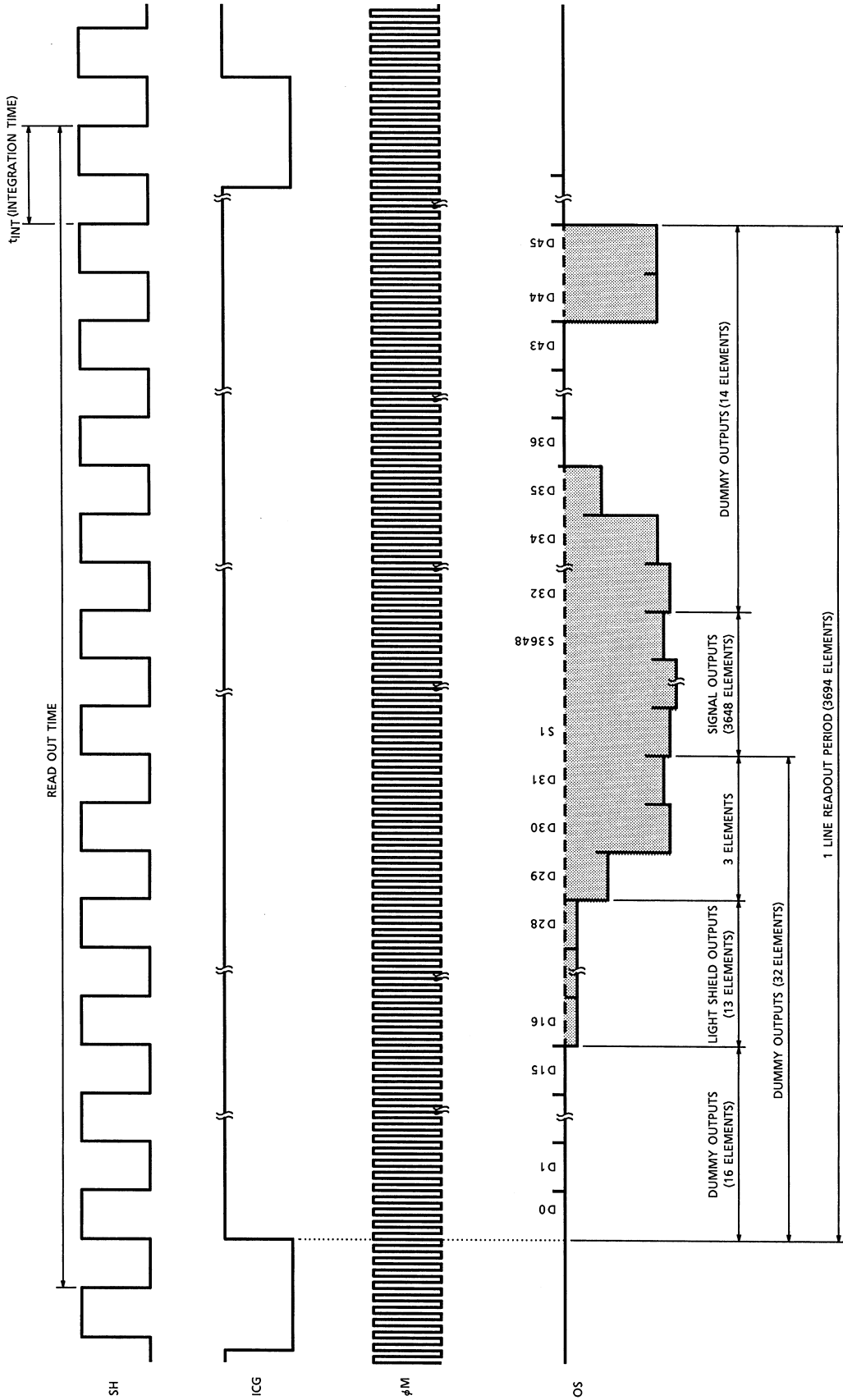
CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
Master Clock Frequency	$f_{\phi M}$	0.8	2.0	2.4	MHz
Data Rate	f_{DATA}	0.2	0.5	0.6	MHz

TIMING CHART



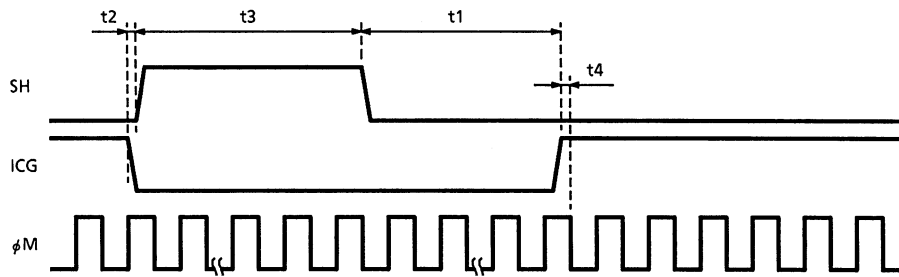
TCD1304DG-6

TIMING CHART (Use electronic shutter function)



TCD1304DG-7

TIMING REQUIREMENTS



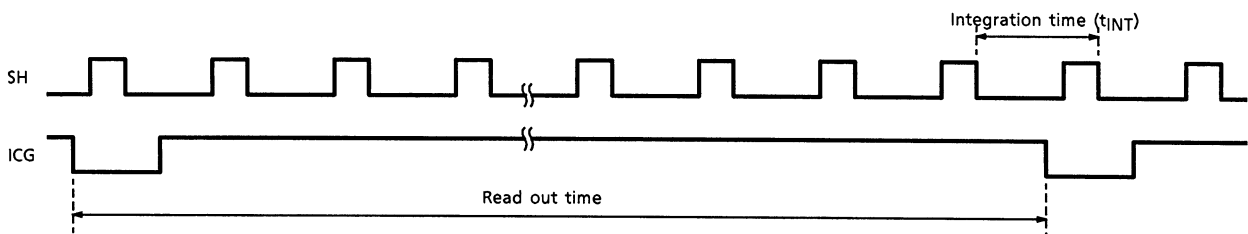
CHARACTERISTIC	SYMBOL	MIN	TYP.	MAX	UNIT
ICG Pulse Delay	t1	1000	5000	—	ns
Pulse Timing of ICG and SH	t2	100	500	1000	ns
SH Pulse Width	t3	1000	—	—	ns
Pulse Timing of ICG and φ M	t4	0	20	*	ns

*: You keep φM "High" Level.

USE ELECTRONIC SHUTTER

Pulse Timing of SH and ICG

- SH cycle = t_{INT}

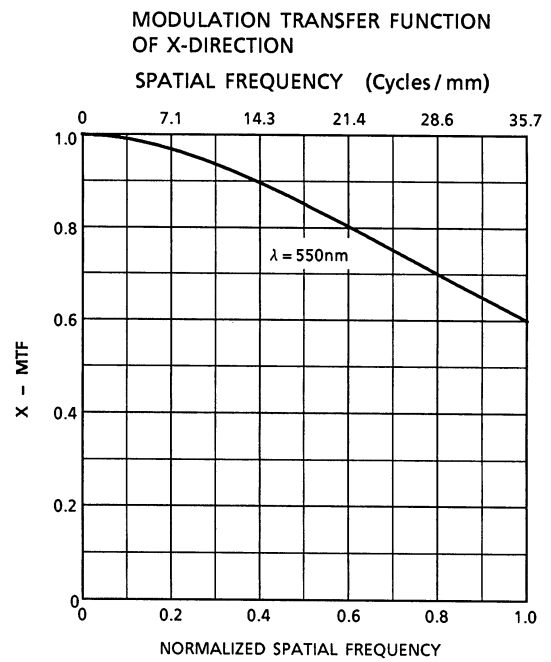
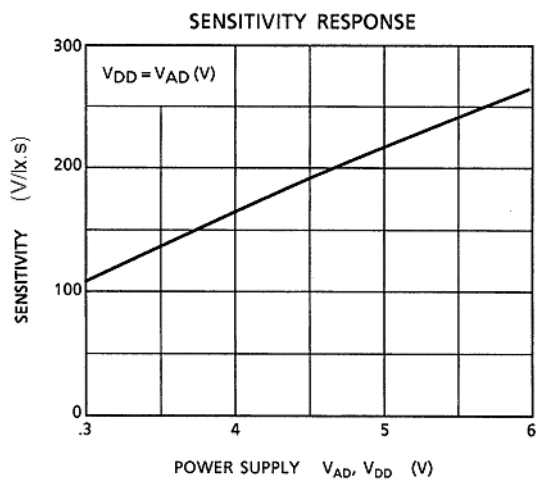
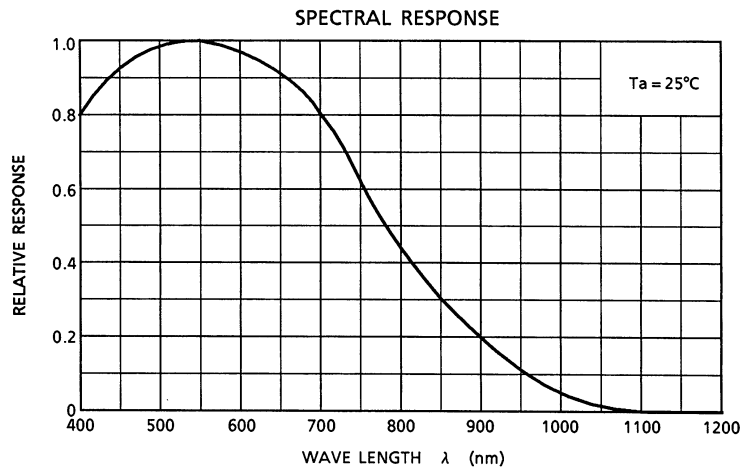


t_{INT} (MIN)=10μs

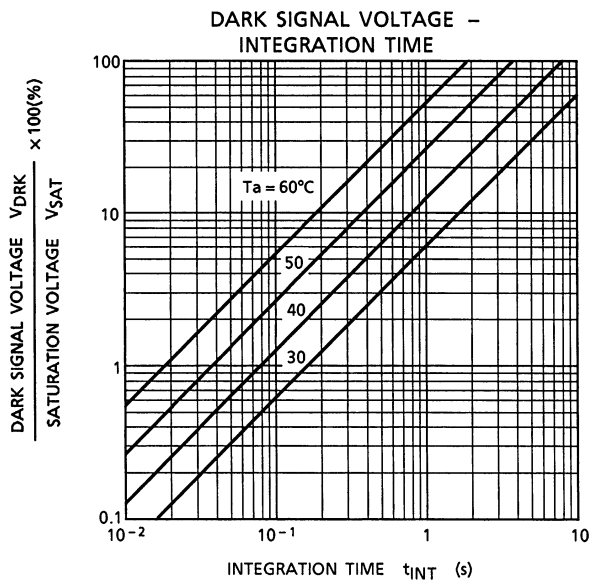
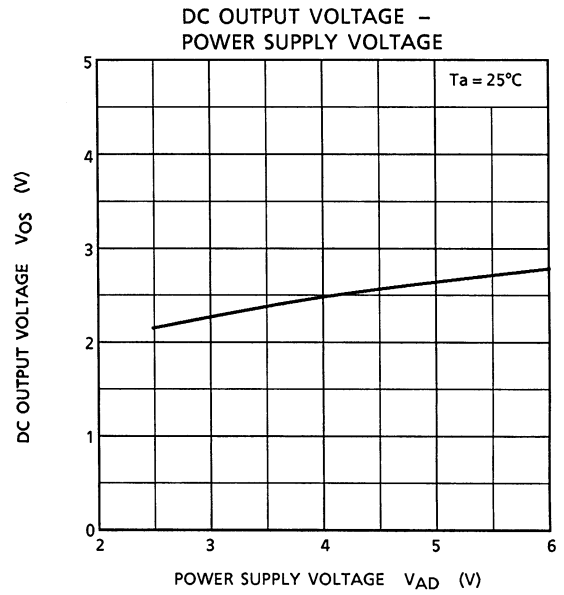
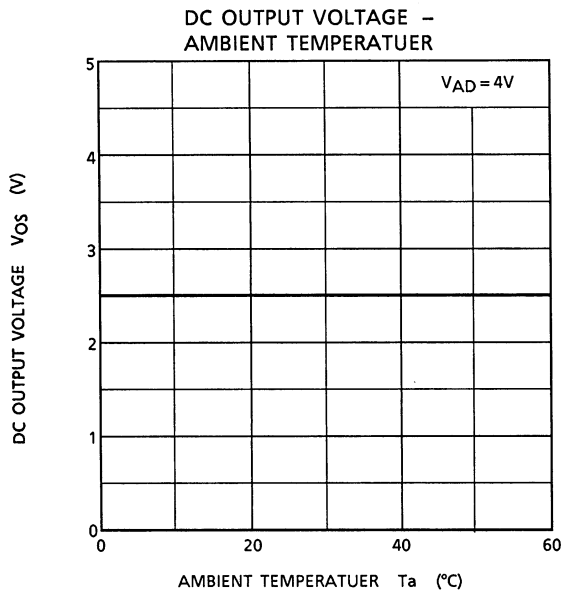
SH pulse width (t₃) should be kept constant.

The illumination of light source must be less than 1000 times of the 450mV output condition at t_{INT} = 10ms.

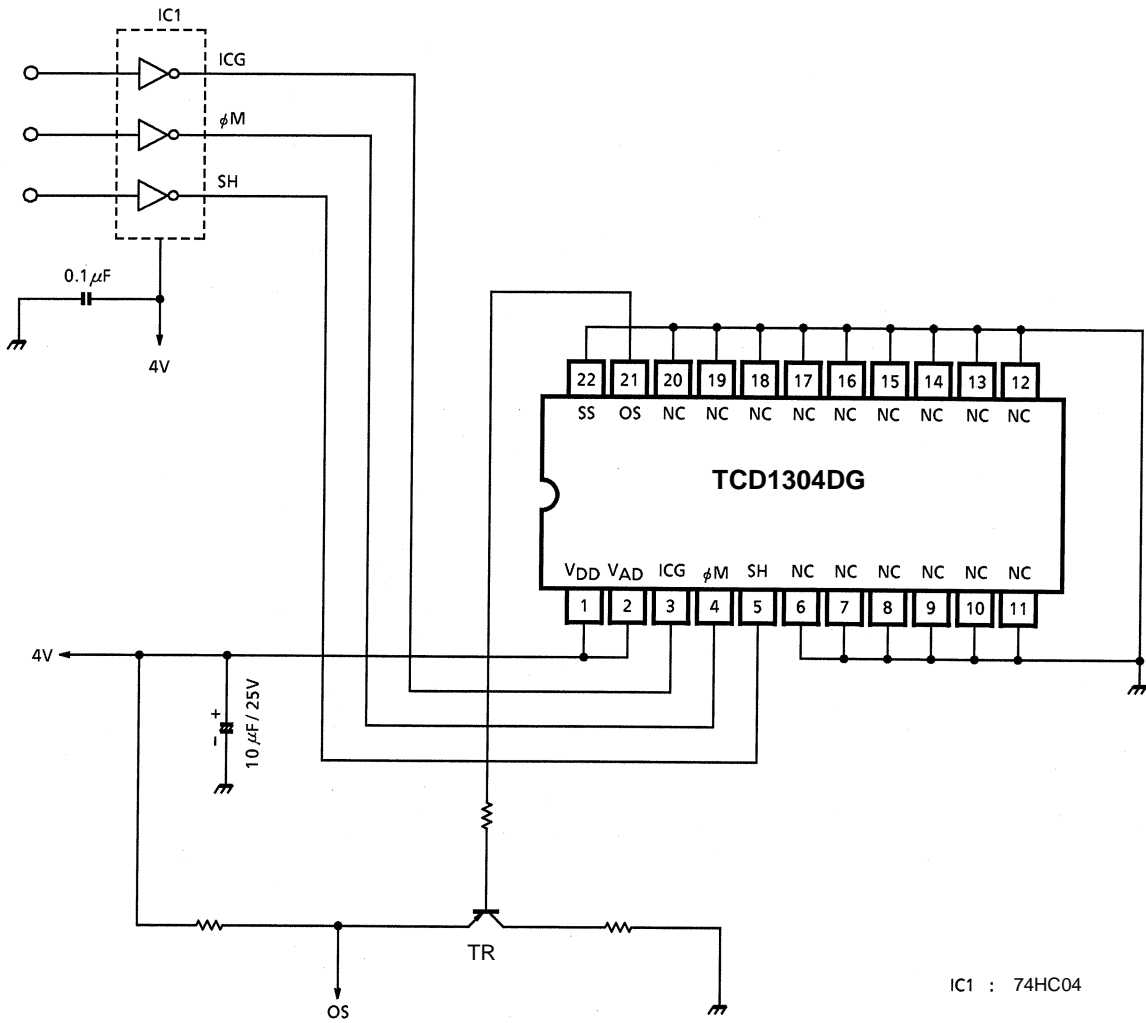
TYPICAL PERFORMANCE CURVES



TYPICAL PERFORMANCE CURVES



TYPICAL DRIVE CIRCUIT



CAUTION**1. Window Glass**

The dust and stain on the glass window of the package degrade optical performance of CCD sensor.

Keep the glass window clean by saturating a cotton swab in alcohol and lightly wiping the surface, and allow the glass to dry, by blowing with filtered dry N₂. Care should be taken to avoid mechanical or thermal shock because the glass window is easily to damage.

2. Electrostatic Breakdown

Store in shorting clip or in conductive foam to avoid electrostatic breakdown.

CCD Image Sensor is protected against static electricity, but interior puncture mode device due to static electricity is sometimes detected. In handing the device, it is necessary to execute the following static electricity preventive measures, in order to prevent the trouble rate increase of the manufacturing system due to static electricity.

- a. Prevent the generation of static electricity due to friction by making the work with bare hands or by putting on cotton gloves and non-charging working clothes.
- b. Discharge the static electricity by providing earth plate or earth wire on the floor, door or stand of the work room.
- c. Ground the tools such as soldering iron, radio cutting pliers or pincer.

It is not necessarily required to execute all precaution items for static electricity.

It is all right to mitigate the precautions by confirming that the trouble rate within the prescribed range.

3. Incident Light

CCD sensor is sensitive to infrared light. Note that infrared light component degrades resolution and PRNU of CCD sensor.

4. Lead Frame Forming

Since this package is not strong against mechanical stress, you should not reform the lead frame.

We recommend to use a IC-inserter when you assemble to PCB.

5. Soldering

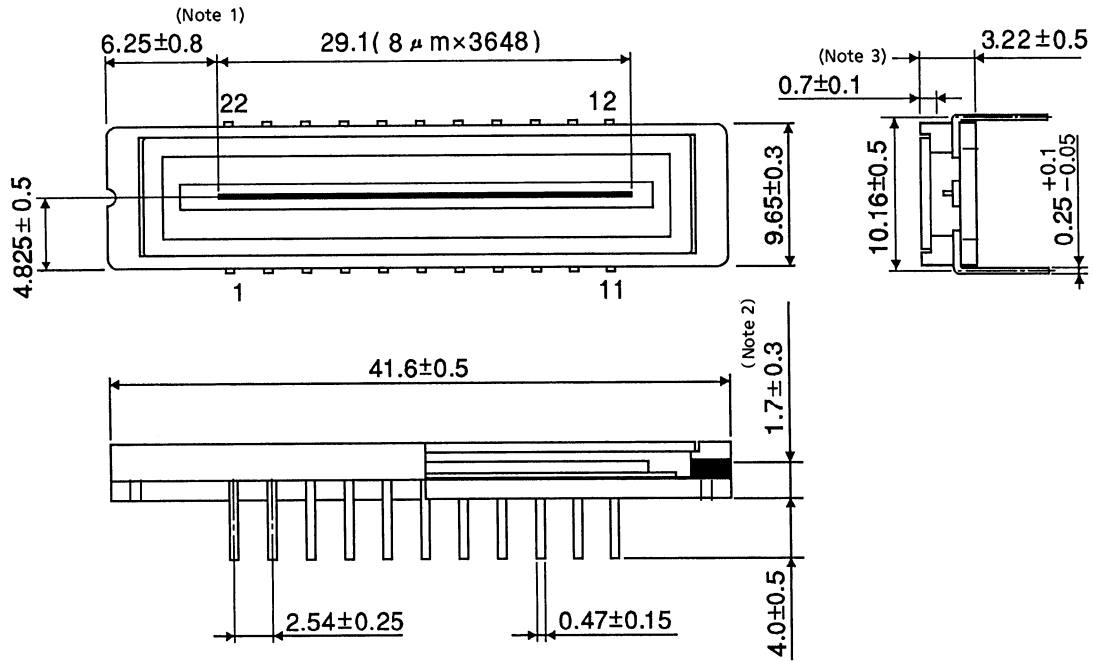
Soldering by the solder flow method cannot be guaranteed because this method may have deleterious effects on prevention of window glass soiling and heat resistance.

Using a soldering iron, complete soldering within 10 seconds for lead temperatures of up to 260°C, or within 3 seconds for lead temperatures of up to 350°C.

PACKAGE DIMENSIONS

WDIP22-G-400-2.54H

Unit : mm



Note 1: No. 1 SENSOR ELEMENT (S1) TO EDGE OF PACKAGE.

Note 2: TOP OF CHIP TO BOTTOM OF PACKAGE.

Note 3: GLASS THICKNES (n = 1.5)

Weight: (3.5g (Typ.))

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